966870-1 <

AMPMODU | AMPMODU Headers

TE Internal #: 966870-1 PCB Mount Header, Horizontal, Wire-to-Board, 16 Position, 2.5 mm Centerline, Fully Shrouded, Tin, Through Hole - Solder, Signal, AMPMODU Headers

View on TE.com >





Connectors > PCB Connectors > PCB Headers & Receptacles



Connector System: Wire-to-Board

Number of Positions: 16

Centerline (Pitch): 2.5 mm

Sealable: No

PCB Mount Orientation: Horizontal

Features

Product Type Features

Mixed & Hybrid Header	No
Connector Shape	Rectangular
PCB Connector Assembly Type	PCB Mount Header

Header Type	Fully Shrouded
Connector System	Wire-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Signal Positions	16
Number of Positions	16
PCB Mount Orientation	Horizontal
Number of Rows	2
Electrical Characteristics	
Nominal Voltage Architecture	12 V
Body Features	
Primary Product Color	Black
Connector & Keying Code	A
Contact Features	

C For support call+1 800 522 6752

PCB Mount Header, Horizontal, Wire-to-Board, 16 Position, 2.5 mm Centerline, Fully Shrouded, Tin, Through Hole - Solder, Signal, AMPMODU Headers



Contact Size	.63mm
Contact Type	Tab
Mating Tab Width	.63 mm
Mating Tab Thickness	.63 mm
Contact Mating Area Plating Material	Tin
Termination Features	
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mounting Holes	Without
Mating Alignment	With
PCB Mount Retention	With
PCB Mount Retention Type	Boardlock
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.5 mm
Dimensions	
Connector Length	35 mm
Connector Width	15.5 mm
Profile Height from PCB	16.2 mm
Usage Conditions	
Operating Temperature (Max)	110 °C
Operating Temperature Range	-40 – 110 °C[-40 – 230 °F]
Operation/Application	
Shielded	No
Circuit Application	Signal
Shielded	
Product Compliance For compliance documentation, visit the product page on TE.com>	
,	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	

PCB Mount Header, Horizontal, Wire-to-Board, 16 Position, 2.5 mm Centerline, Fully Shrouded, Tin, Through Hole - Solder, Signal, AMPMODU Headers



Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Halogen Content

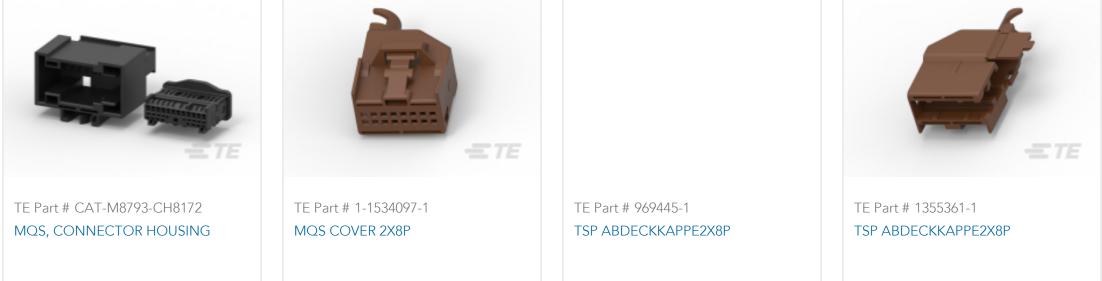
Solder Process Capability

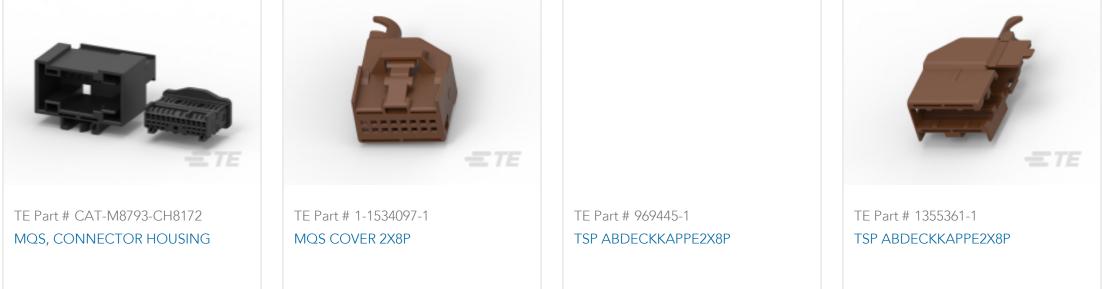
Wave solder capable to 240°C

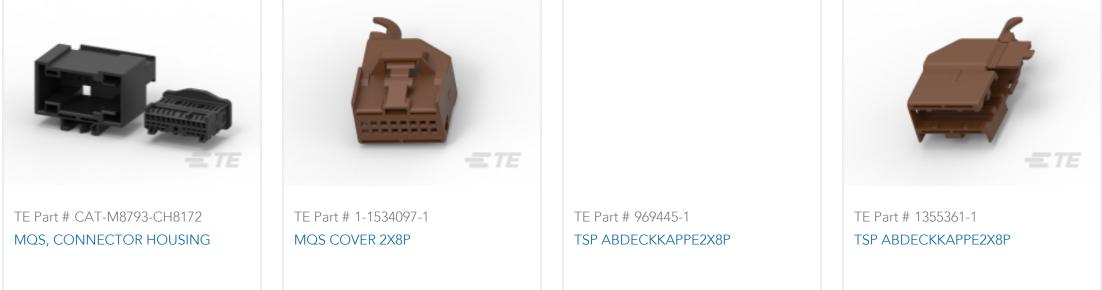
Product Compliance Disclaimer

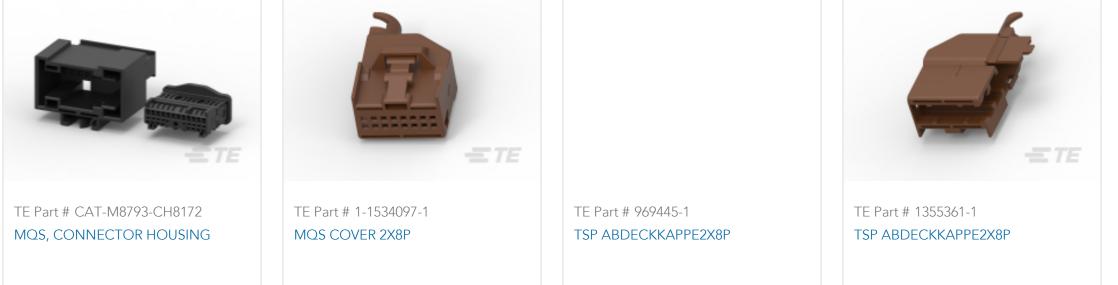
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts









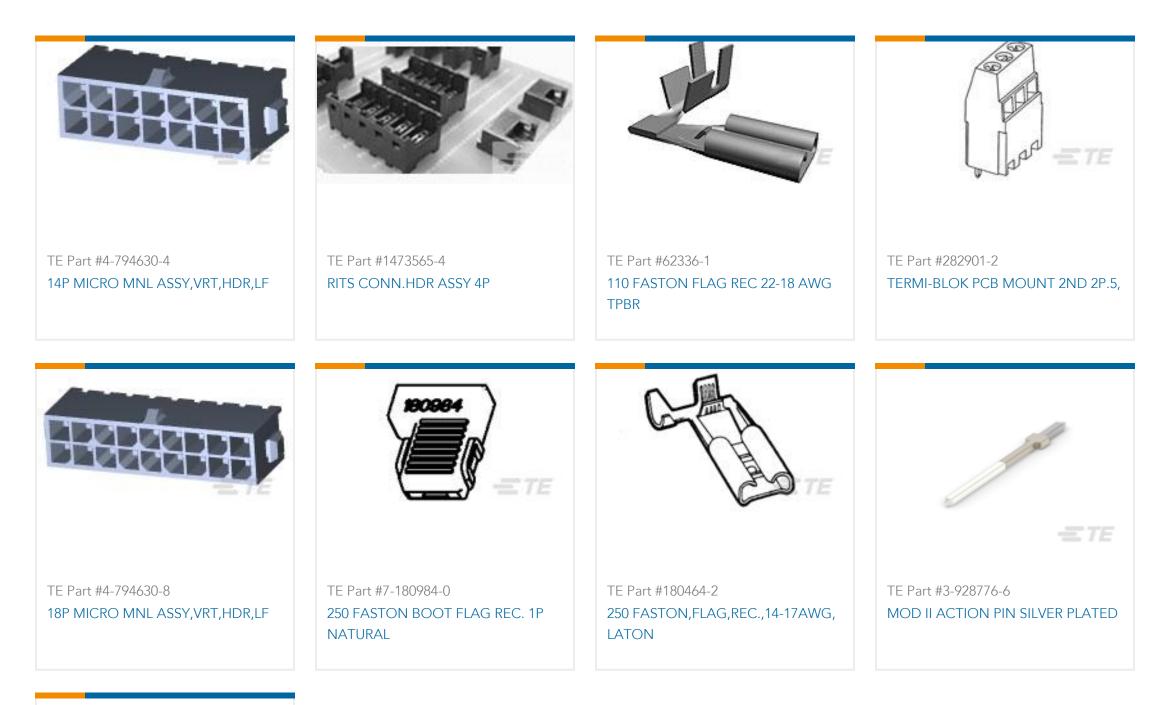
Also in the Series AMPMODU Headers



Customers Also Bought

PCB Mount Header, Horizontal, Wire-to-Board, 16 Position, 2.5 mm Centerline, Fully Shrouded, Tin, Through Hole - Solder, Signal, AMPMODU Headers







TE Part #826467-8 8P MOD II SHROUDED HEADER, ST

Documents

Product Drawings MOD2 ST-WANNE 2X 8P

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_966870-1_C.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_966870-1_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_966870-1_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the Terms and Conditions of use.

Product Specifications

C For support call+1 800 522 6752

PCB Mount Header, Horizontal, Wire-to-Board, 16 Position, 2.5 mm Centerline, Fully Shrouded, Tin, Through Hole - Solder, Signal, AMPMODU Headers



Product Specification

English